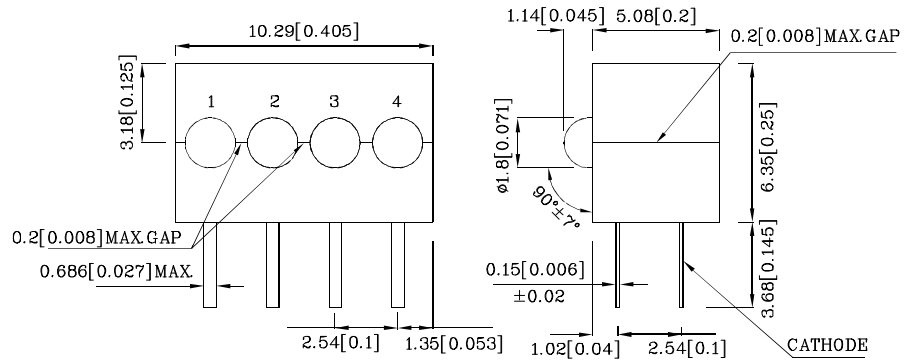


**Features**

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- 5V internal resistor
- RoHS Compliant



**Package Schematics**

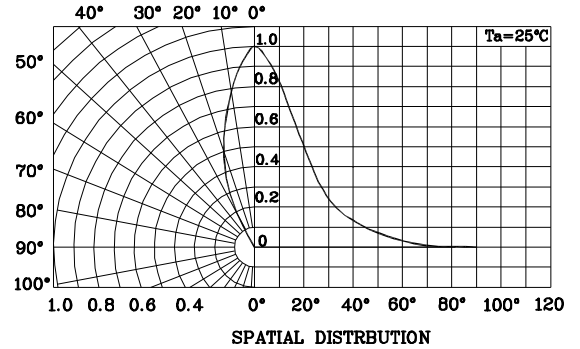
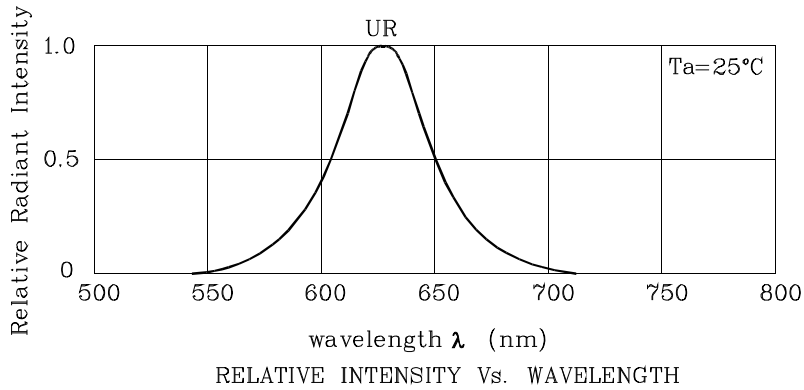


- Notes:  
 1. All dimensions are in millimeters (inches).  
 2. Tolerance is ±0.25(0.01") unless otherwise noted.  
 3. Specifications are subject to change without notice.

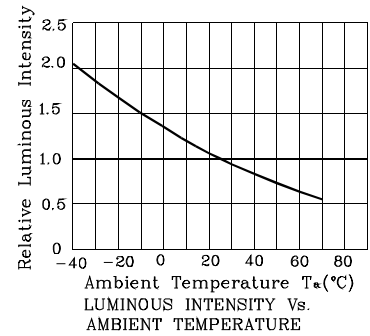
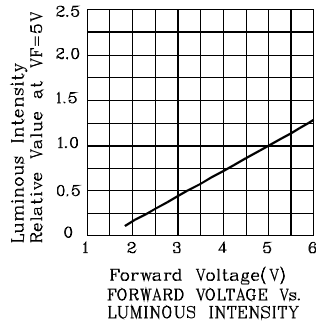
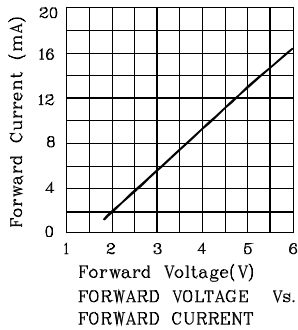
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Voltage	V <sub>F</sub>	6	V
Power Dissipation	P <sub>D</sub>	85	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +70	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit
Forward Current (Typ.) (V <sub>F</sub> =5V)	I <sub>F</sub>	13	mA
Forward Current (Max.) (V <sub>F</sub> =5V)	I <sub>F</sub>	17.5	mA
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission (Typ.) (V <sub>F</sub> =5V)	λ <sub>P</sub>	627	nm
Wavelength of Dominant Emission (Typ.) (V <sub>F</sub> =5V)	λ <sub>D</sub>	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) (V <sub>F</sub> =5V)	Δλ	45	nm

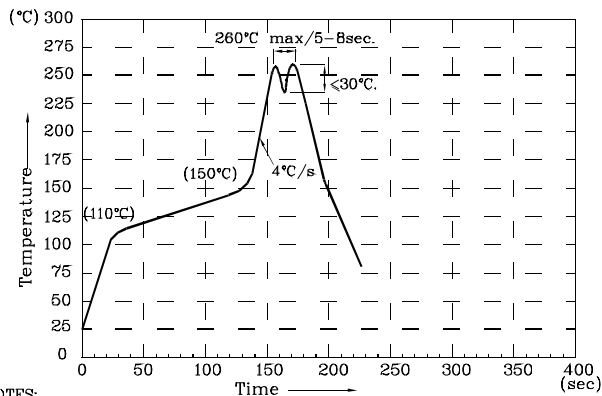
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (V <sub>F</sub> =5V) mcd		Wavelength nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XNF4ZUR46D5V	Red	GaAsP/GaP	Red Diffused	4	11	627	40°



❖ UR



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- NOTES:
1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
  2. Do not apply stress on epoxy resins when temperature is over 85°C.
  3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
  4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
  5. No more than once.

Remarks:

If special sorting is required (e.g. binning based on Luminous intensity/ luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity/ luminous flux: +/-15%

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

